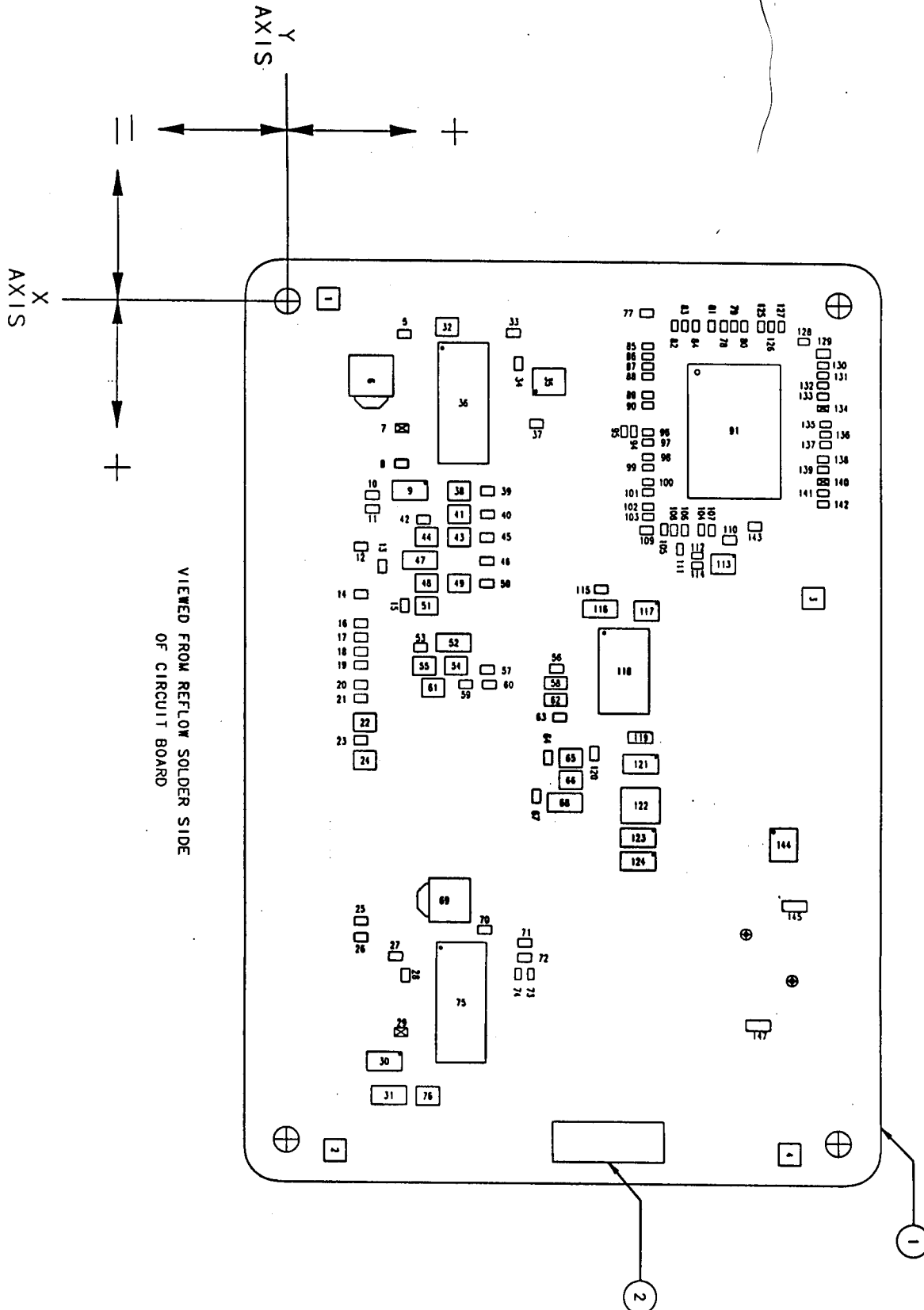


DELPHI DELCO ELECTRONICS SYSTEMS
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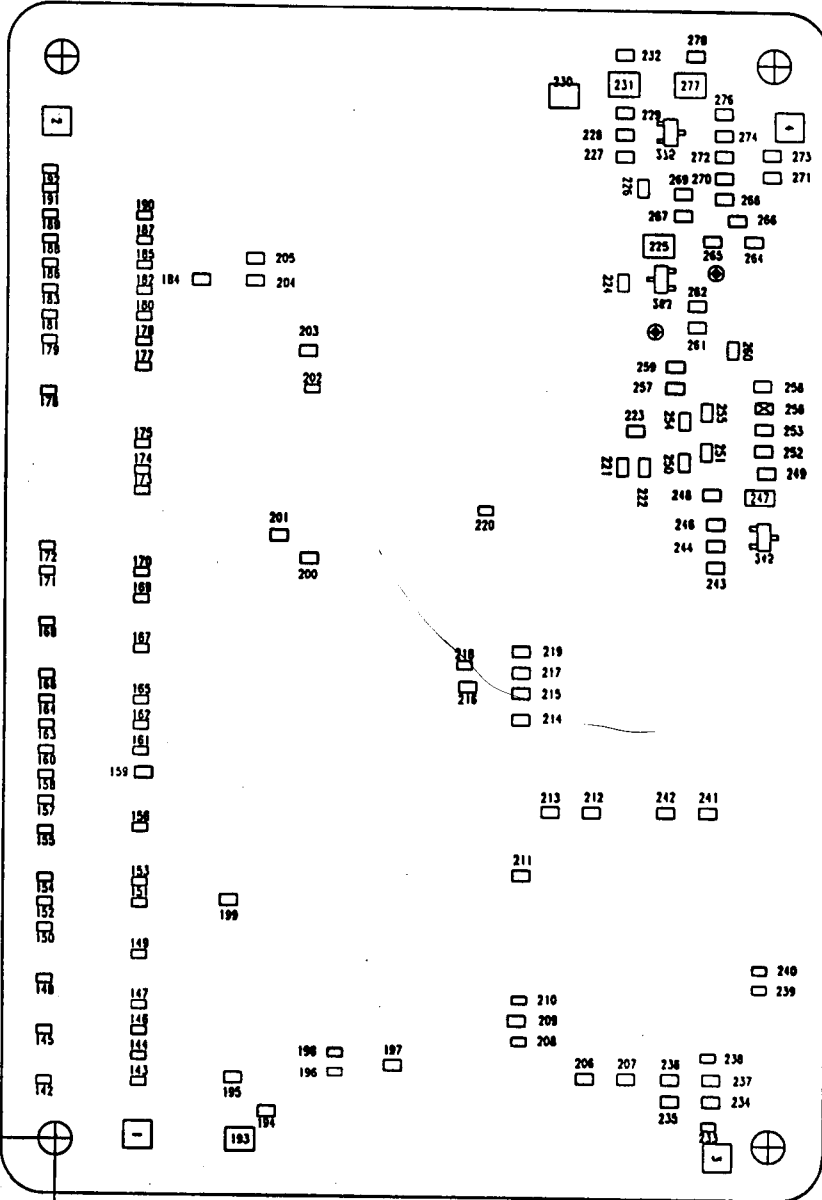


VIEWED FROM REFLOW SOLDER SIDE
 OF CIRCUIT BOARD

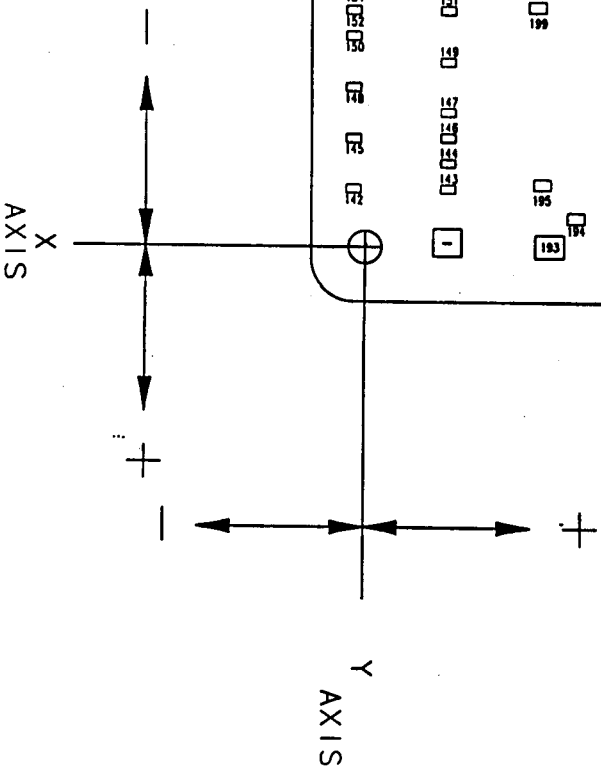
NOTES:

1. SECURE SMC'S TO THE REFLOW SOLDER SIDE OF THE CIRCUIT BOARD USING SOLDER PASTE ITEM 3 PER PROCESS SPECIFICATION.

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VIEWED FROM WAVE SOLDER SIDE
 OF CIRCUIT BOARD



NOTES:

1. SECURE SMC'S TO THE WAVE SOLDER SIDE OF THE CIRCUIT BOARD PERPROCESS SPECIFICATION USING PRIMARY ADHESIVE ITEM 2 OR OPTIONAL ADHESIVE ITEM 3.